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ON Semiconductor®

FDB9503L-F085

P-Channel PowerTrench® MOSFET

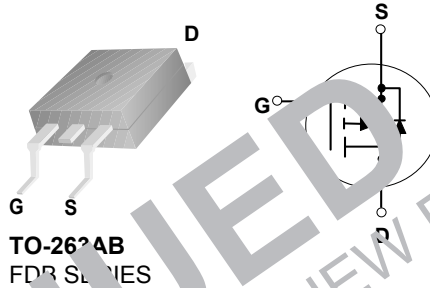
- 40 V, - 110 A, 2.6 mΩ

Features

- Typical $R_{DS(on)}$ = 2.0 mΩ at $V_{GS} = -10V$, $I_D = -80 A$
- Typical $Q_{g(tot)}$ = 196 nC at $V_{GS} = -10V$, $I_D = -80 A$
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Electrical Power Steering
- Integrated Starter/Alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems



MOSFET Maximum Ratings $T_J =$ °C unless otherwise noted.

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	±16	V
I_D	Drain Current - Continuous ($V_{GS} = -10$) (Note 1)	-110	A
	Pulse Drain Current	See Figure 4	
E_{AS}	Single Pulse Avalanche Energy (Note 2)	984	mJ
P_D	Power Dissipation	333	W
	Derate Above 25°C	2.22	W/°C
T_J, T_{STG}	Operating and Storage Temperature	-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.45	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient (Note 3)	43	°C/W

Notes:

- 1: Current is limited by wirebond configuration.
- 2: Starting $T_J = 25^\circ C$, $L = 0.3mH$, $I_{AS} = -81A$, $V_{DD} = -40V$ during inductor charging and $V_{DD} = 0V$ during time in avalanche.
- 3: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB9503L	FDB9503L-F085	TO-263AB	330mm	24mm	800 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

$B_{V_{DS}}$	Drain-to-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-40	-	-	V
I_{DSS}	Drain-to-Source Leakage Current	$V_{DS} = -40\text{V}, T_J = 25^\circ\text{C}$ $V_{GS} = 0\text{V}, T_J = 175^\circ\text{C}$ (Note 4)	-	-	-1	μA mA
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 16\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	-1.0	-1.5	-2.0	V
$R_{DS(on)}$	Drain to Source On Resistance	$I_D = -80\text{A}, V_{GS} = -4.5\text{V}, T_J = 25^\circ\text{C}$	-	2.1	3.3	$\text{m}\Omega$
		$I_D = -80\text{A}, T_J = 25^\circ\text{C}$	-	2.0	2.6	$\text{m}\Omega$
		$V_{GS} = -10\text{V}, T_J = 175^\circ\text{C}$ (Note 4)	-	2.9	3.7	$\text{m}\Omega$

Dynamic Characteristics

C_{iss}	Input Capacitance		-	832	-	pF
C_{oss}	Output Capacitance	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	5620	-	pF
C_{rss}	Reverse Transfer Capacitance		-	102	-	pF
R_g	Gate Resistance	$f = 1\text{kHz}$	-	20	-	Ω
$Q_g(\text{ToT})$	Total Gate Charge at 10V	$V_{GS} = 10, -10\text{V}, V_{DS} = -32\text{V}, I_D = -30\text{A}$	-	15.5	23.5	nC
$Q_g(\text{th})$	Threshold Gate Charge	$V_{GS} = 0, 2\text{V}, I_D = -30\text{A}$	-	26	-	nC
Q_{gs}	Gate-to-Source Gate Charge		-	14	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge		-	22	-	nC

Switching Characteristics

t_{on}	Turn-On Time		-	-	146	ns
$t_{d(on)}$	Turn-On Delay		-	12	-	ns
t_r	Rise Time	$V_{DD} = -20\text{V}, I_D = -80\text{A}$	-	86	-	ns
$t_{d(off)}$	Turn-Off Delay	$V_{GS} = -10\text{V}, R_{GEN} = 6\Omega$	-	700	-	ns
t_{fall}	Fall Time		-	310	-	ns
t_{off}	Turn-Off Time		-	-	1538	ns

Drain-Source Diode Characteristics

V_{SD}	Source-to-Drain Diode Voltage	$I_{SD} = -80\text{A}, V_{GS} = 0\text{V}$	-	-	-1.25	V
		$I_{SD} = -40\text{A}, V_{GS} = 0\text{V}$	-	-	-1.2	V
t_{rr}	Reverse-Recovery Time	$I_{SD} = -80\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}, V_{DD} = -32\text{V}$	-	124	186	ns
Q_{rr}	Reverse-Recovery Charge		-	214	321	nC

Note:

4: The maximum value is specified by design at $T_J = 175^\circ\text{C}$. Product is not tested to this condition in production.

Typical Characteristics

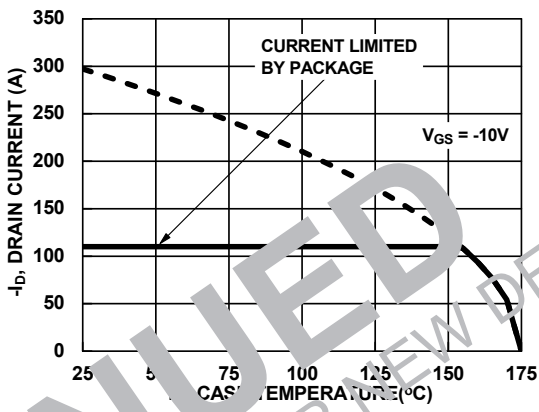
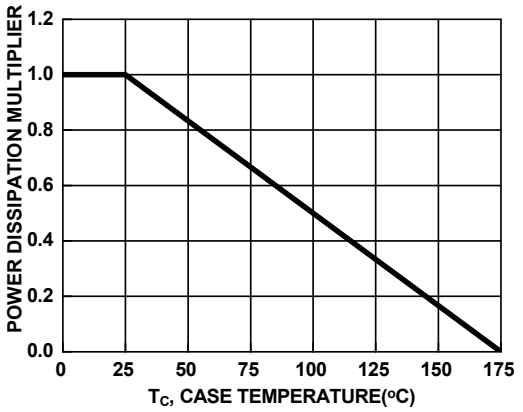


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs. Case Temperature

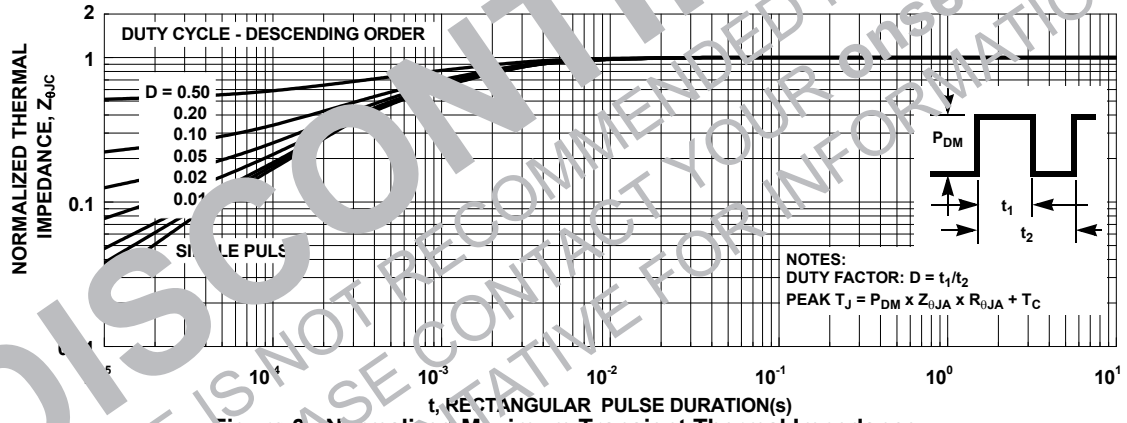


Figure 3. Normalized Maximum Transient Thermal Impedance

Typical Characteristics

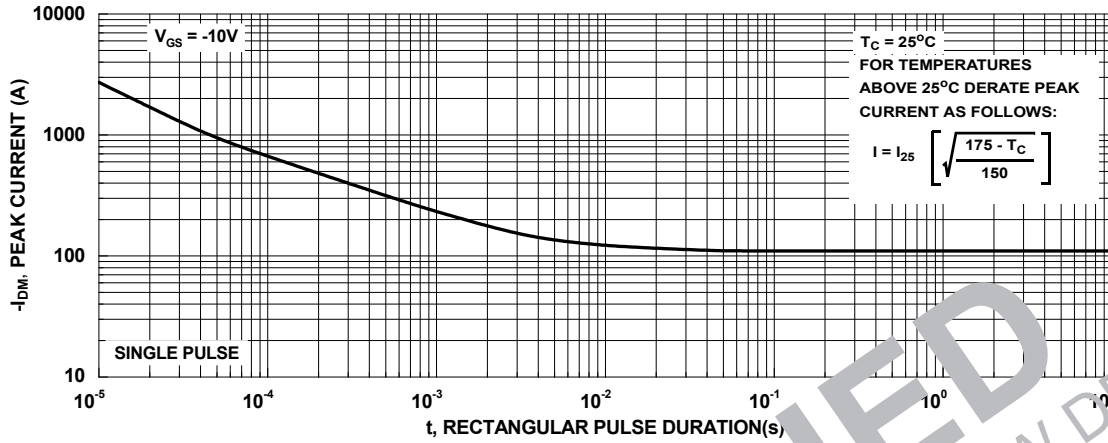


Figure 4. Peak Current Capability

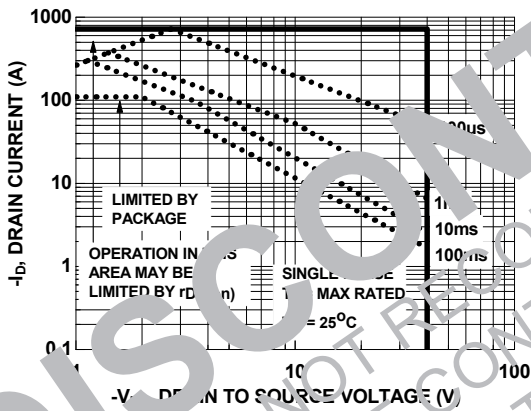
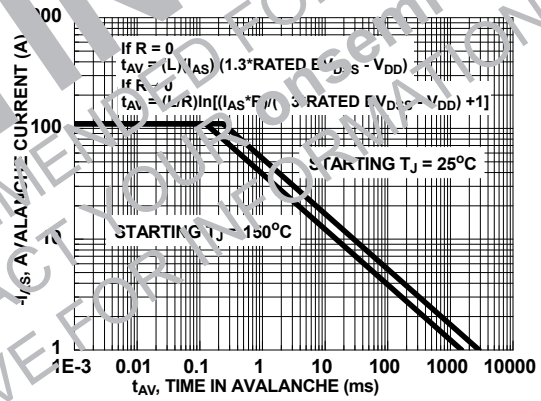


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

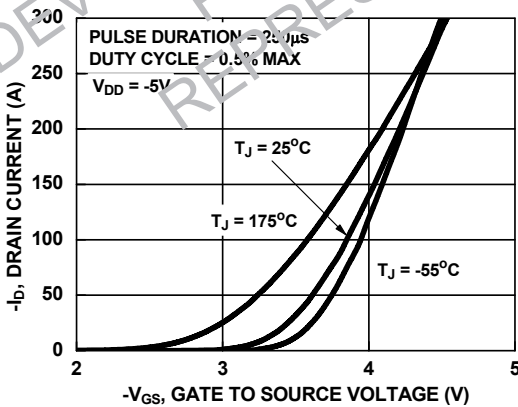


Figure 7. Transfer Characteristics

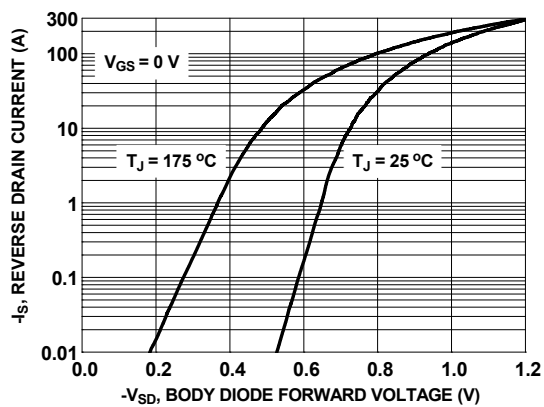


Figure 8. Forward Diode Characteristics

Typical Characteristics

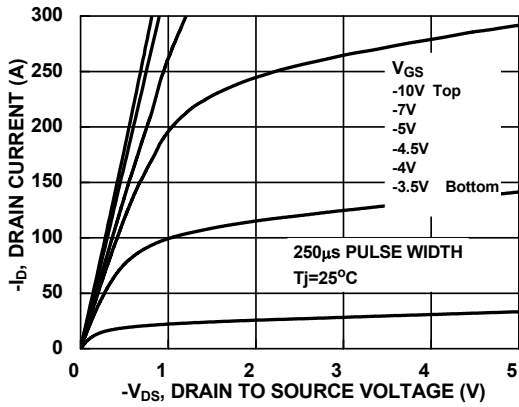


Figure 9. Saturation Characteristics

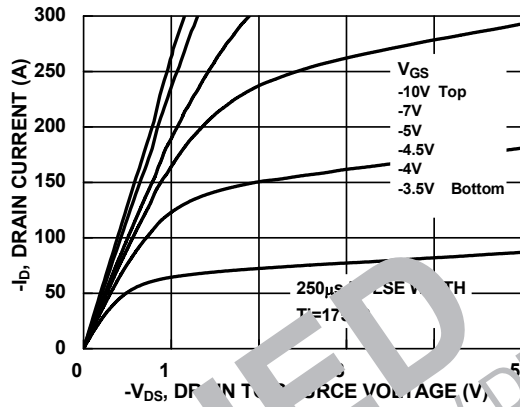


Figure 10. Saturation Characteristics

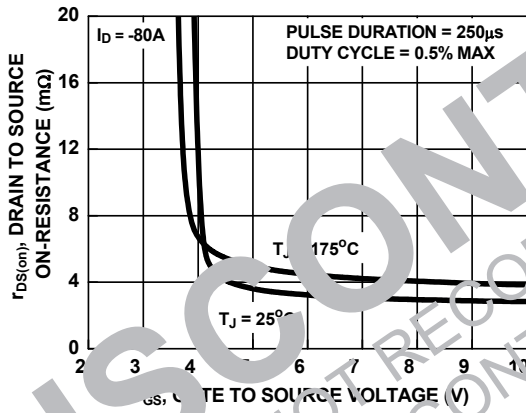


Figure 11. $R_{DS(on)}$ vs. Gate Voltage

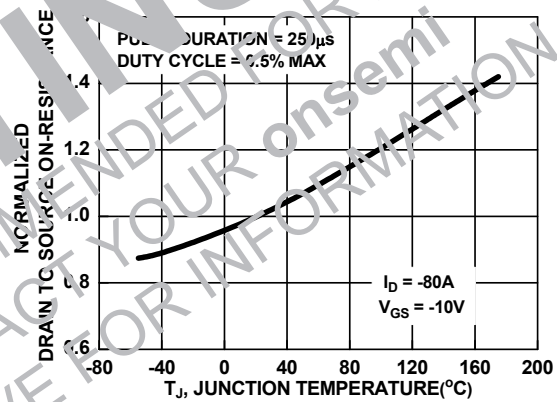


Figure 12. Normalized $R_{DS(on)}$ vs. Junction Temperature

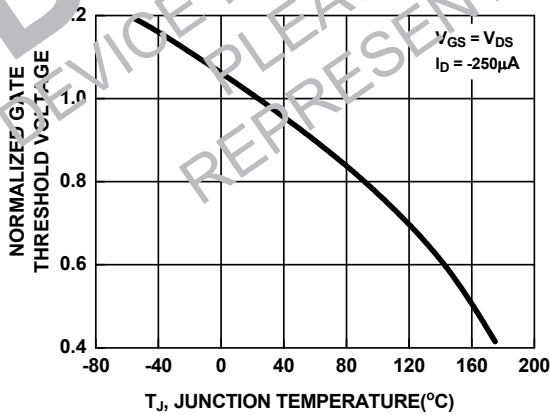


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

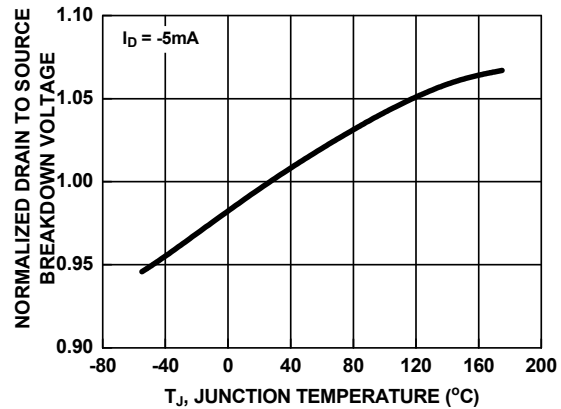


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

Typical Characteristics

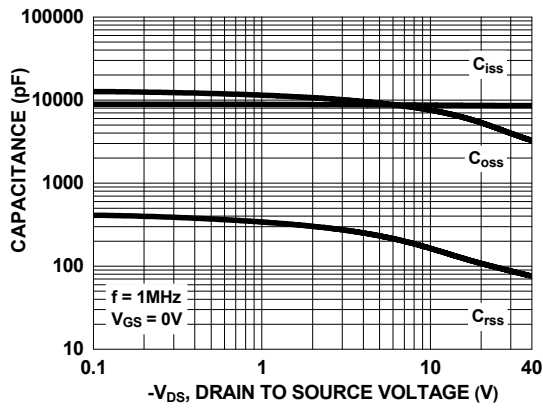


Figure 15. Capacitance vs. Drain to Source Voltage

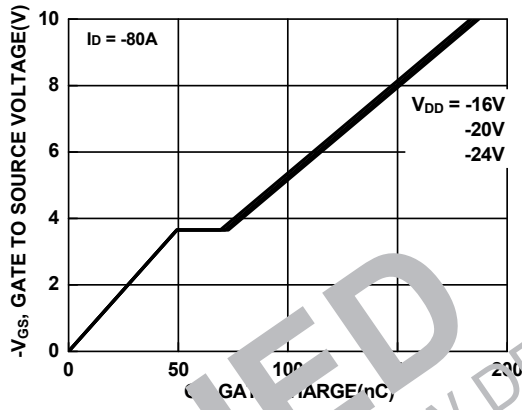



Figure 16. Gate Charge vs. Gate to Source Voltage

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